

CHIP SPECIFICATION BRIEF OVERVIEW

CSULB
CECS 460

WHAT IS A CHIP SPECIFICATION?

- The design team creates the “official document” for the SOC/Chip design
- It contains all the information that one would need to know in order to include the SOC/Chip into a design
- The information needs to address several areas:
 - The physical characteristics (package type, pin count, pin out, current requirements, etc.)
 - The hardware implementation (what does the chip contain, what can one do with it, etc.)
 - The software interface (how does one program the device, what are the register addresses/contents)

CHIP SPECIFICATION IN 460

- The goal of 460 is to produce an SOC (chip design)
- We write our own IP (AISO, UART, etc.)
- We instantiate commercially available IP (TramelBlaze)
- We interface to devices (memory)
- The Chip Spec is the final deliverable for your work this semester and should be prepared with care
- It should document the design through the work that you have accomplished
- You should do your best to follow the recommended format

EXAMPLES

- For the LPC2148 the chip specification is the UM10139 document (the more functionality contained within a device the more information that needs to be included in the specification)
- For the Artix 7 FPGA there is the Artix 7 users guide
- Every device meant for public consumption must have a well written chip specification. This will enable the users to quickly integrate the device into their own designs with as little confusion as possible



OUR CLASS

Chip Specification Template

- I worked for a company, Valence Semiconductors (now defunct), that needed a clear methodology documented for the engineering organization
- We produced a Chip Specification Template that has been placed in the lectures folder on BeachBoard
 - This is for reference only - there is way too much information required that we will not need to document
 - The next page will outline the contents of our chip spec that will be expected to be included

CHIP SPEC COMPONENTS

- The chip specification should thoroughly define the design of the chip as a written document
- The reader should understand what are the components of the design, what the purpose of each is, and how the information flows together
- The Verilog code is for reference and should be included as an organized appendix - keep the flow clear
- The assembly code should also be included in the appendix but should be thoroughly described under the banner of “software”

FORMAT

- The document should have a table of contents identifying which page number each item may be found on
- This means that every page must have a page number
- Do your best to make it a professional looking document

DUE DATE

- The project due date will be defined as the last day of class. My desire is that no one works on the project during finals
- The Chip Spec will be due at the beginning of the final exam

CHIP SPECIFICATION OUTLINE

- I. Introduction
- II. Documents
 - A. Applicable External Documents
 - B. Applicable Internal Documents
- III. Requirements
- IV. Top Level Design
 - A. Description
 - B. Block Diagram
 - C. Data Flow Description
 - D. I/O
 - 1. Signal Names
 - 2. Pin Assignments
 - 3. Electrical Characteristics
 - E. Clocks
 - F. Resets
 - G. Software
- V. Externally Developed Blocks
 - A. Description
 - B. Block Diagram
 - C. I/O
 - D. Register Map
- VI. Internally Developed Blocks
 - A. Description
 - B. Block Diagram
 - C. I/O
 - D. State Machines
 - E. Register Map
 - F. Verification
- VII. Chip Level Verification
- VIII. Chip Level Test